

JUN 16 2004

PatentCustomer No.: 31561
Docket No. 9249-US-PA
Application No.: 10/604,791**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Lee et al.

Application No. : 10/604,791

Filed : 2003/08/18

For : SEMICONDUCTOR PACKAGE MODULE AND
MANUFACTURING METHOD THEREOF

Art Unit : 2811

Examiner : NGUYEN, CUONG QUANG

OFFICE

RESPONSE TO RESTRICTION REQUIREMENTASSISTANT COMMISSIONER FOR PATENTS
Arlington, VA 22202

Dear Sirs,

In response to the Office Action, mailed on June 1, 2004, Applicant would like to elect Group II, claims 11-23, drawn to a method of making a semiconductor device, classified in class 438, subclass 100+. Please cancel Group I, claims 1-10, drawn to a semiconductor device, classified in class 257, subclass 723 without waiver, prejudice or disclaimer.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN IP OfficeDate: June 16, 2004

By:

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